Display Elektronik GmbH

DATA SHEET

LCD-MODULE

DEM 256128A FGH-PW

Product Specification

Ver.: 1

Revision History

VERSION	DATE	Note
0	24.05.2016	First Issue
1	01.12.2016	Add FPC Bending Rules

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1. General Specification

The Features is described as follow:

■ Module Dimension: 80.00 x 54.00 x 9.50 mm

■ View Area: 70.70 x 38.80 mm

Active Area: 66.54 x 33.26 mm

■ Number of Dots: 256 x 128

■ Dot Size: 0.24 x 0.24 mm

■ Dot Pitch: 0.26 x 0.26mm

■ LCD Type: FSTN Positive Transflective

■ Duty: 1/128 DUTY, 1/12 BIAS

■ View Direction: 6 o'clock

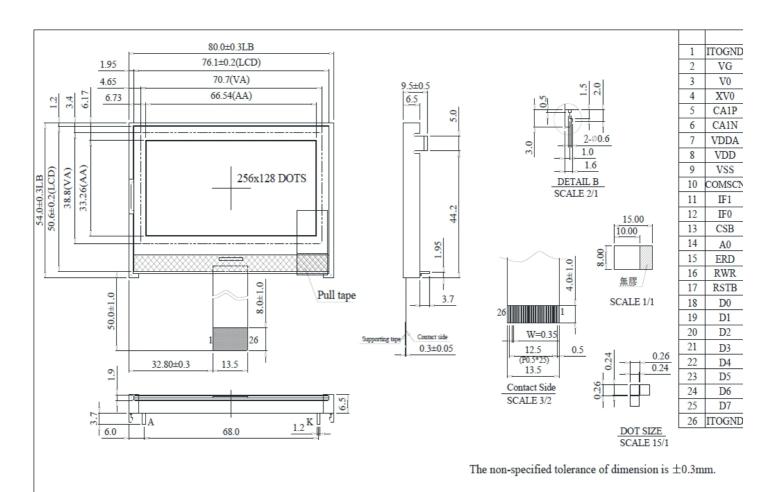
■ Backlight Type: LED, White

■ IC: ST75256 (Sitronix)

2. Interface Pin Function

Pin No.	Symbol			Description		
1	ITOGND	ESD PI	ESD PIN			
2	VG	Power c	of SEG-	drivers		
3	V0	Positive	operat	ing voltage of COM-drivers		
4	XV0	Negativ	e opera	ting voltage of COM-drivers		
5	CA1P	DC/DC	Voltage	converte pin		
6	CA1N	DC/DC	Voltage	converte pin		
7	VDDA	+3.3V				
8	VDD	+3.3V				
9	VSS	ground				
10	COMSCN	Set scar	n direct	ing of COM		
11	IF1	These pir	ns select	interface operation mode.		
		IF1	IF0	MPU interface type		
	IF0	L	L	4-line serial interface		
12		L	Н	IIC serial interface		
		Н	L	8-bit 6800 parallel interface		
		Н	Н	8-bit 8080 parallel interface		
		Note: Ref	er to "Par	allel / Serial Interface'' for detailed information.		
13	CSB	Chip sel	lect inp	ut pin		
14	A0	Whethe	r the ac	cess is related to data or command		
15	ERD	Read or write enable terminal				
16	RWR	Read/Write execution control pin				
17	RSTB	Reset input pin				
18~25	D0~D7	Data bu	s line			
26	ITOGND	ESD PI	N			

3. Counter Drawing

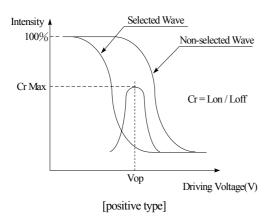


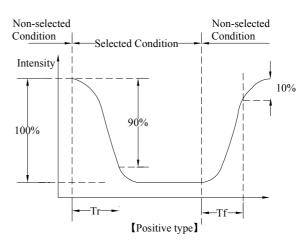
4. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR ≧ 2	0	_	30	ψ= 180°
View Angle	θ	CR ≧ 2	0	_	60	ψ= 0°
View Angle	θ	CR ≧ 2	0	_	45	ψ= 90°
	θ	CR ≧ 2	0	_	45	ψ= 270°
Contrast Ratio	CR	_	_	5	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	_	250	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



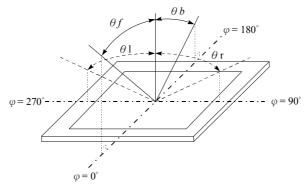


Conditions:

Operating Voltage : Vop Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of Viewing Angle(CR≥2)



5. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
MPU Interface Input Voltage	Vin	-0.3	_	V _{DD} +0.3	V
Digital Power Supply Voltage	V _{DD} -Vss	-0.3	_	4.0	V
LCD Power supply voltage	V0- XV0	-0.3	_	19.0	V

6. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{\text{DD}}\text{-}V_{\text{SS}}$	_	3.0	3.3	3.6	٧
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	V_{OP}	Ta=25℃	14.2	14.5	14.8	V
		Ta=70℃	_	_	_	V
Input High Volt.	V _{IH}	_	0.7 V _{DD}	_	V_{DD}	V
Input Low Volt.	VIL	_	Vss	_	0.3 V _{DD}	V
Output High Volt.	Vон	_	0.8 V _{DD}	_	V _{DD}	V
Output Low Volt.	Vol	_	Vss	_	0.2 V _{DD}	V
Supply Current	I_{DD}	V _{DD} =3.3V	_	1.5	_	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

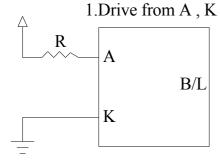
7. Backlight Information

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	96	120	mA	V=3.5V
Supply Voltage	V	3.3	3.5	3.7	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminance	IV	840	1050		cd/m ²	ILED=96mA
(Without LCD)	IV	040	1030	_	Cu/III-	ILED-90IIIA
LED Life Time						ILED=96mA
(For Reference	_	_	50000	_	Hr.	25°C, 50%RH-60%RH,
only)						(Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: 50000 hours is only an estimate for reference.

LED B\L Drive Method



8. Reliability

Content of Reliability Test (Wide Temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60□,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C, 90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C +25°C +70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS= ± 600 V (Contact), ± 800 V (Air), RS= 330Ω CS= 150 pF 10 times	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

9. Inspection specification

NO	Item		Criterion					
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 						
02	Black or white spots on LCD (display only)	three white o	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 					
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y) / $ $X \longrightarrow X$ 3.2 Line type : (2 ↓ ▼ Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense 2 As round type	2.5		
04	Polarizer bubbles	If bubbles are v judge using blac specifications, r to find, must cho specify direction	ck spot not easy eck in	Size Φ $ Φ \le 0.20 $ $ 0.20 < Φ \le 0.50 $ $ 0.50 < Φ \le 1.00 $ $ 1.00 < Φ $ $ Total Q TY$	Acceptable Q TY Accept no dense 3 2 0 3	2.5		

NO	Item		Criterion				
05	Scratches	Follow NO.3 LCD black	spots, white spots, con	tamination			
06	Scratches Chipped glass	Symbols Define: x: Chip length y: 0	Chip width z: Chip Glass thickness a: LCI is face and crack between y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length of y: Chip width Not over viewing	thickness D side length n panels: x: Chip length x≤ 1/8a x≤ 1/8a	2.5		
		1/2t < z ≦ 2t	area Not exceed 1/3k	x≤1/8a			
		⊙If there are 2 or more	chips, x is the total leng	gth of each chip.			

NO	Item	Criterion	AQL
06	Glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad: y: Chip width x: Chip length z: Chip thickness y ≤ 0.5mm x ≤ 1/8a 0 < z ≤ t 6.2.2 Non-conductive portion: y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t oilf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. oilf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length y ≤ 1/3L x ≤ a	2.5

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.	0.65 2.5
09	Bezel	8.3 Backlight doesn't light or color wrong.9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	0.65 2.5 0.65
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 	2.5 2.5 0.65 2.5
10	PCB · COB	 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 	2.5 0.65
		10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2	2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
NO	General appearance	Criterion 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 0.65
		12.9 LCD pin loose or missing pins.	0.65 0.65
		12.10 Product packaging must the same as specified on	0.03
		packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	

10. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) DISPLAY have the right to change the passive components, including R3, R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) DISPLAY have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, DISPLAY have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending

